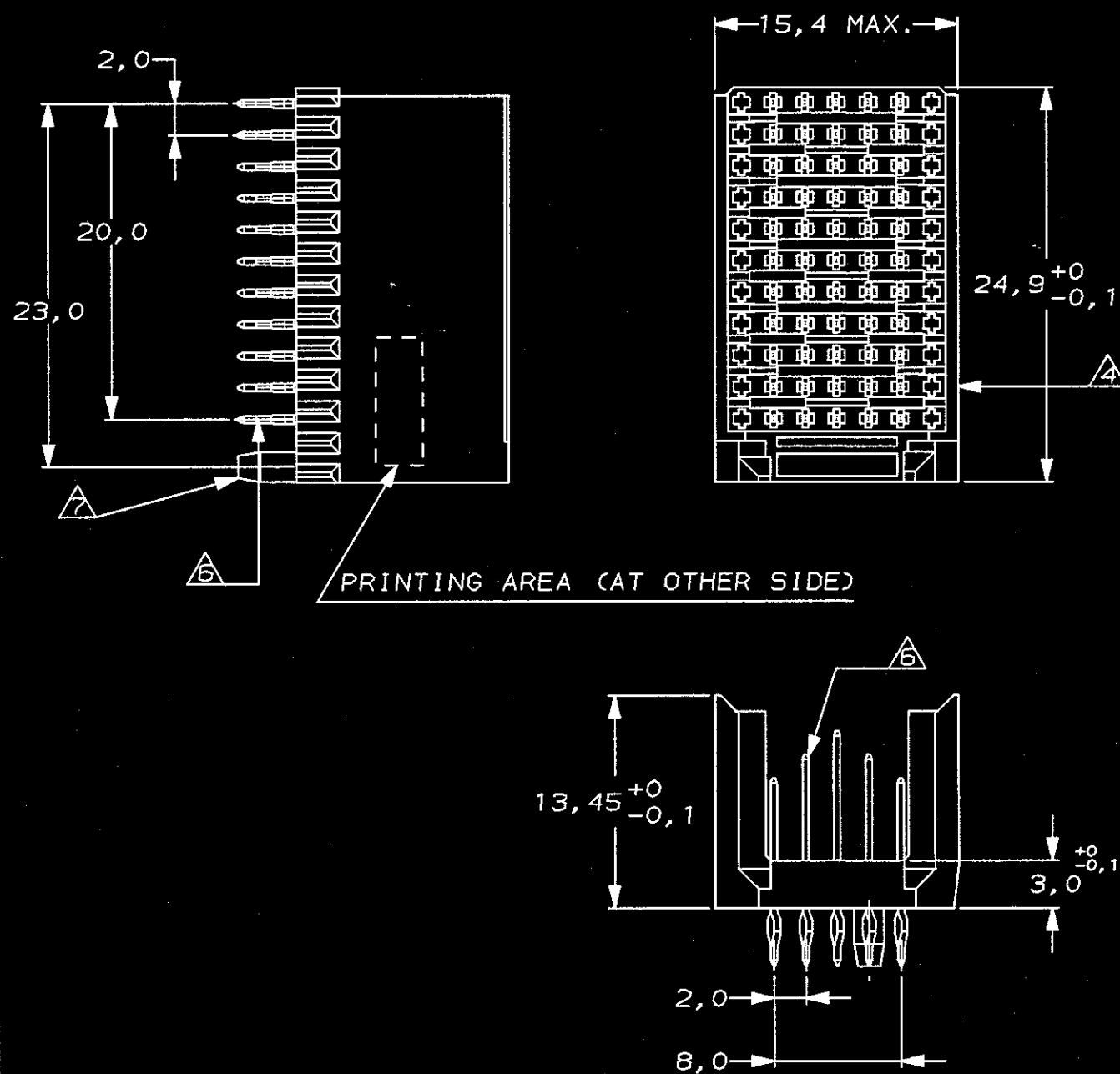


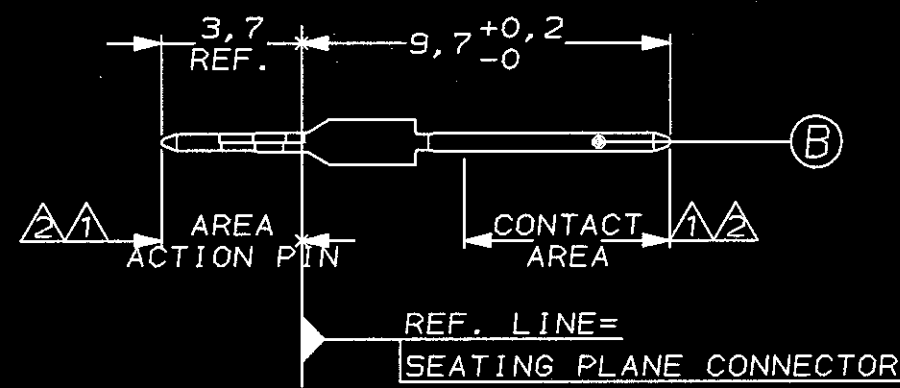
# CONNECTOR ASSEMBLY EXEMPLARY LOADED



### NOTES:

- △ PLATING CONTACT AREA: 0,8µm Au MIN. OVER 1,3µm Ni MIN.  
ACTION PIN : 0,5µm SnPb MIN. OVER 1,3µm Ni MIN.
- △ PLATING CONTACT AREA: 1,3µm Au MIN. OVER 1,3µm Ni MIN.  
ACTION PIN : 0,5µm SnPb MIN. OVER 1,3µm Ni MIN.
- △ MATERIAL CONTACT: PHOSPHORBRONZE.  
MATERIAL HOUSING: GLASSFILLED POLYESTER.
- △ CONNECTOR PRINTED WITH PARTNUMBER AND DATECODE.
- △ PLATED-THROUGH HOLES AT 2x2mm SQUARE GRID.  
TOTAL 55 HOLES.
- △ FOR ACTUAL PIN LOADING SEE "CONTACT LAYOUT"
- △ POLARIZING NIPPLE
- △ CONNECTOR ASSEMBLY LUBRICATED WITH BELLCORE APPROVED LUBRICANT. TECHNICAL REFERENCE:  
TR-NWT-001217 ISSUE 1, SEPT 1992.

# CONTACT DIMENSIONS

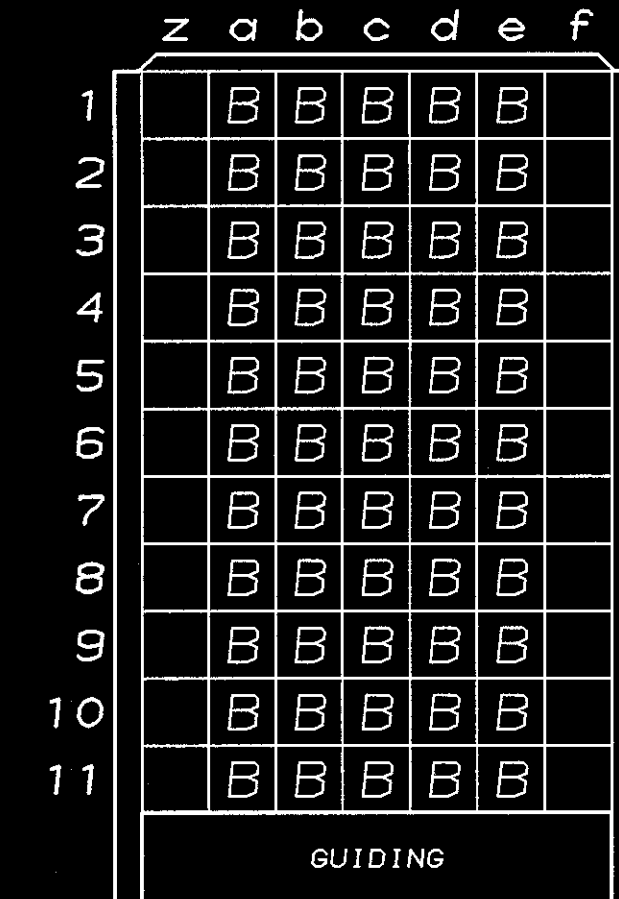


DO NOT SCALE  
DIMENSIONS IN mm

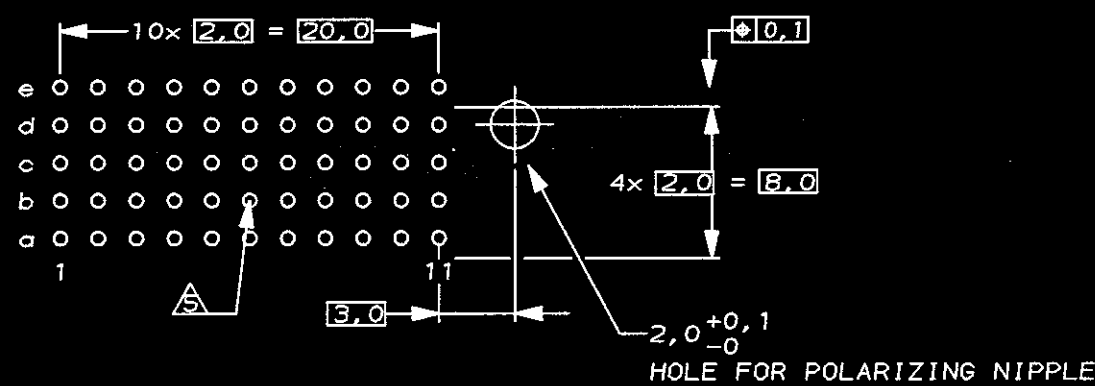
METRIC

THIRD ANGLE  
PROJECTION

# CONTACT LAYOUT



### RECOMMENDED PCB-HOLE LAY-OUT COMPONENT SIDE SHOWN



### P.C.B. HOLE DIM. ACTION PIN

- DRILLED HOLE: 0,7±0,025mm
- FIN. HOLE : 0,55 TO 0,65mm
- Cu-thks : 0,025 TO 0,050mm
- SnPb-thks : 0,004 TO 0,010mm

△	△	△	1-188232-9
△	△	△	188232-9
△	△	△	188232-1
FINISH		MATERIAL	PARTNUMBER

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THIS DRAWING IS UNPUBLISHED				RELEASED FOR PUBLICATION	
C	EH-0884-95	S.E. BM	17-JUL-95	AMP HOLLAND B.V. s-Hertogenbosch, The Netherlands.	
B	EH-0456-95	JvdK BM	11-APR-95	NAME Z-PACK 2mm HM TYPE C	
A	EH-0875-94	JvdK BM	29-NOV-94	55 POS. MALE BACKPANEL	
O	EH-0390-94	LvdH BM	30-JUN-94	CONNECTOR ASSEMBLY	
LTR.	REVISION RECORD	DR.	CHK.	DATE	
DR. : L.V.D.HEIJDEN	CHK. : B.M001J	APP. : L.V.SOEST	DWG.No.	REV.LTR.	SHEET
DATE: 30-JUN-94	DATE: 30-JUN-94	DATE: 29-06-94	C-188232	C	1 OF 1